

AMENDMENTS TO THE CLAIMS

This listing of claims will replace all prior versions, and listings, of claims in the application:

1. (original) An apparatus comprising:
an integrated circuit package substrate;
a plurality of integrated circuit die attached to the integrated circuit package substrate;
and
a stiffener strip attached to the integrated circuit package substrate and surrounding two or more of the plurality of integrated circuit die.
2. (original) An apparatus according to Claim 1, further comprising:
underfill material disposed between the plurality of integrated circuit die and the integrated circuit package substrate.
3. (original) An apparatus comprising:
an integrated circuit package;
an integrated circuit die coupled to the integrated circuit package; and
a stiffener portion coupled to the integrated circuit package and surrounding the integrated circuit die.
4. (original) An apparatus according to Claim 3, further comprising:
underfill material disposed between the integrated circuit die and the integrated circuit package.

5. (original) An apparatus according to Claim 3, wherein the stiffener portion and the integrated circuit package define a well in which the integrated circuit die is disposed, the apparatus further comprising:

thermally-conductive material disposed in the well and in contact with the integrated circuit die.

6. (original) An apparatus according to Claim 5, further comprising:

a heat sink coupled to the stiffener portion and in contact with the thermally-conductive material.

7. (currently amended) A method comprising:

placing a plurality of integrated circuit die on respective ones of a plurality of mounting locations of an integrated circuit package substrate; and

placing a stiffener strip ~~defining a plurality of openings~~ on the integrated circuit package substrate,

wherein the plurality of integrated circuit die and the plurality of mounting locations are disposed in respective ones of ~~the~~ a plurality of openings defined by the stiffener strip.

8. (original) A method according to Claim 7, further comprising:

soldering the plurality of integrated circuit die to the respective mounting locations.

9. (original) A method according to Claim 8, further comprising:

dispensing underfill material on the integrated package substrate adjacent to one or more of the mounting locations.

10. (original) A method according to Claim 7, further comprising:

singulating one of the plurality of integrated circuit die and a respective mounting location of the integrated package substrate.

11. (original) A system comprising:

a microprocessor comprising:

an integrated circuit package;

an integrated circuit die coupled to the integrated circuit package; and

a stiffener portion coupled to the integrated circuit package and surrounding the integrated circuit die; and

a double data rate memory electrically coupled to the microprocessor.

12. (original) A system according to Claim 11, wherein the stiffener portion and the integrated circuit package define a well in which the integrated circuit die is disposed, the microprocessor further comprising:

thermally-conductive material disposed in the well and in contact with the integrated circuit die.

13. (original) A system according to Claim 12, the microprocessor further comprising:

a heat sink coupled to the stiffener portion and in contact with the thermally-conductive material.

14. (original) A system according to Claim 11, further comprising:

a motherboard electrically coupled to the microprocessor and to the memory.